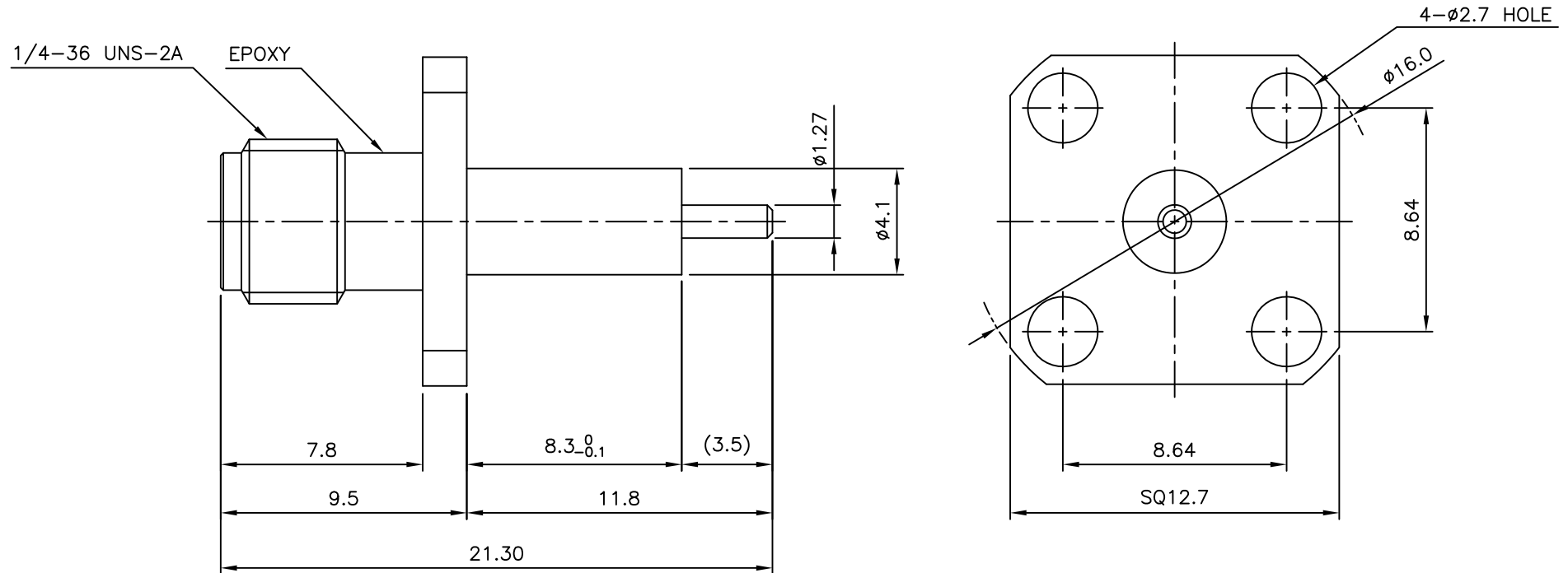
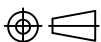


REVISION					
REV	DESCRIPTION			DRAWN	APPR
1	Initial Registration			S.H.KIM	2022.09.21.
2	EPOXY 작업 후 핀 회전 방지로 인한 납시바늘 삭제 및 널링 추가			S.Y.EUN	2022.11.01.



3	INSULATOR	1	TEFLON		DIN03313-N/1
2	CONTACT	1	BeCu C17300	Gold Plate 1.27 μ m	DCT04327-5/1
1	BODY	1	SUS303	Passivate	DBD04855-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2022. 11. 01.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle ±1°	APPROVED BY	S.H.KIM		
MATERIAL _____	CHECKED BY	TITLE SMA50 SOLDER END JS-4H			
	DRAWN BY				
FINISH _____	SCALE 4/1	UNIT mm		A4	DWG NO. CN04073-7/1
					REVISION 1